

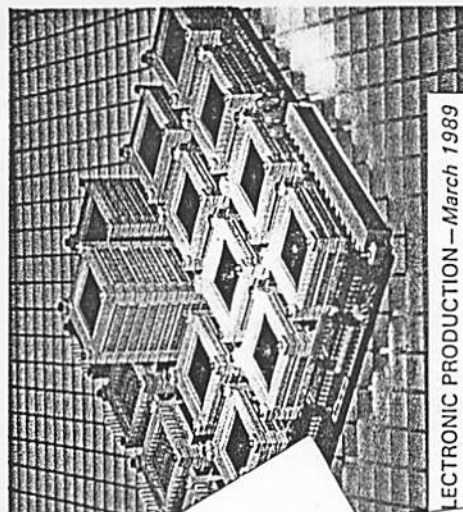
computer brainwave

Dowdy buys into

ACE

£250,000 cash for chip connector

ELECTRONICS PACKAGING



ELECTRONIC PRODUCTION - March 1988

Partitioning - The Track Solution

of partitioning large electronic by using interconnected stacks has developed by Dowdy Interconnect. A key technology, known as track system, is described by Mike Anstey.

project. The company a take it on and conti patenting process but. a US patent was straight away, the U suffered a series of d will only be granted n Their most interest ion is the Chip I because it relies on a change of thinking interconnection industry, it will fac struggle to be accep Dowdy Electro connect, howe sufficient faith in l acquire the manuf development rig invested £250,000. "The idea beh changes in th electronics comp from discrete c vlsi devices, m whole method using pcbs can said Anstey.

Performs the most exciting dev... enables microchips to be intercon... Vertical tracks: Air circulating around... chip improves thermal management... allowing more microprocessor capability...

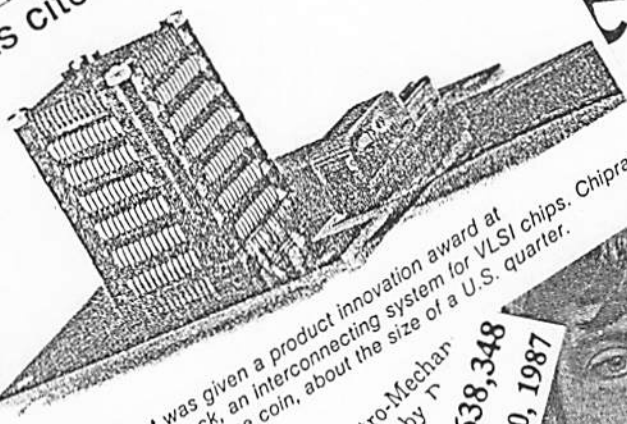
REFERENCE PREVIEW

ems

In so far as avionics is concerned Burke looks to an answer from the hybrid manufacturers and in the construction of complete circuits rather than parts of circuits.

He also looks towards the possibility of further integration with three dimensional circuitry similar to that pioneered by Mike Anstey of ICDC.

Innovative products cited in U.K.



Dowdy Electronic Interconnect was given a product innovation award at INTERNEPCON/UK85 for its Chiprack, an interconnecting system for VLSI chips. Chiprack is shown here next to a British 50-pence coin, about the size of a U.S. quarter.



Mike Anstey: pioneered 3-D circuitry.

CHIP RACK, the first three-dimensional racking system for the interconnection of VLSI chips, made its debut at the Royal Society last week. A working prototype, carrying the Chip Rack was shown to Mike Anstey, claims that the system is far superior to the traditional printed circuit board for connecting advanced VLSI circuitry. Once designers become used to designing on silicon, much of the complexity of interconnecting incorporated on a consultancy basis and Anstey now works with Dowdy on a consultancy basis and who took up the idea for development. Anstey now works with Dowdy on a consultancy basis and who took up the idea for development. Anstey now works with Dowdy on a consultancy basis and who took up the idea for development.

By Peter Large, Technology Correspondent... A WAY of learning microchips that might make the multi-dimensional computer commonplace has been taken up by the Dowdy group in £250,000 research later.

In so far as an... Burke... from the... variations.

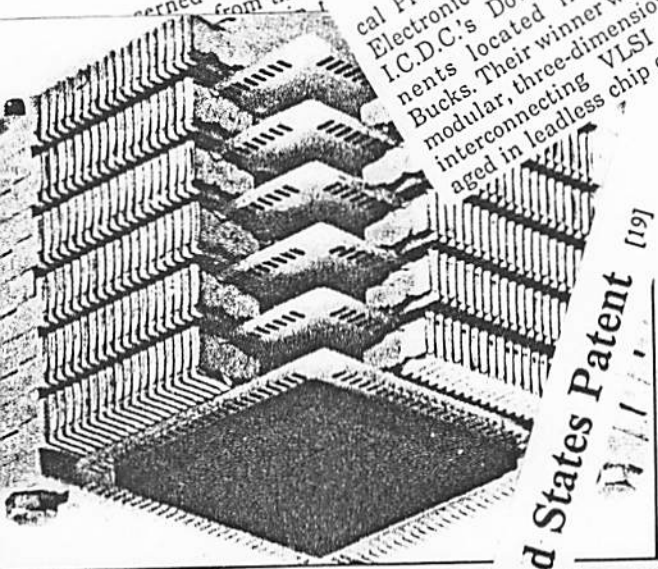
Brighton, England - Awards were presented to three British companies Electro-Mechanics at INTERNEPCON/UK85 here in recognition of outstanding product innovation. "Most Innovative Electro-Mechanical Product" was garnered by Dowdy Electronic Interconnect, a unit of I.C.D.C.'s Dowdy Electronic Components located in High Wycombe, Bucks. Their winner was "Chiprack," a modular, three-dimensional system for interconnecting VLSI devices packaged in leadless chip carriers.

4,638,348 Jan. 20, 1987

Imagine a connector system that will allow you to put the contents of a single eurocard onto a pcb less than a quarter of the area; that makes parallel processing simple and faster; is easy to upgrade and test; and finally that makes diagnostics and testing a doddle. These are some of the claims for Dowdy Interconnect's Chiprack. Project manager Ron Wilkins see its potential as a follow on from traditional based products - "Industry has given engineers the chance to develop their own chips, now they have the possibility of designing their own chip computer using Chiprack. Chris Evans-Pugh went to Dowdy Interconnect's Los Angeles centre to find out more.

Space saving - 3-D modular connector system

INTERCONNECTION



United States Patent 4,638,348

Patent Number: 4,502,098 Date of Patent: [45]

Apr. 26, 1983

I am writing to inform you under Section 18(4), 8321375 reported that your patent application number 8321375 of the Act and Rules. Your application is therefore granted